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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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October 2009

QVE00118 Phototransistor Optical Interrupter Switch

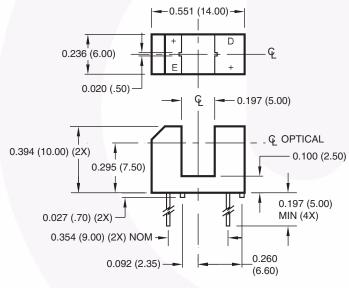
Features

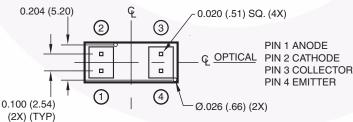
- No contact sensing
- 5mm gap
- 0.5mm aperture width
- Low profile
- PCB mount
- Transistor output

Description

The QVE00118 consists of an infrared light emitting diode coupled to an NPN silicon phototransistor packaged into an injection molded housing. The housing is designed for wide-gap, non-contact sensing.

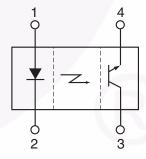
Package Dimensions







Schematic



Notes:

- 1. Dimensions for all drawings are in inches (millimeters).
- 2. Tolerance of ± .010 (.25) on all non-nominal dimensions unless otherwise specified.

Absolute Maximum Ratings (TA = 25°C unless otherwise specified)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating	Units		
T _{OPR}	Operating Temperature	-55 to +100	°C		
T _{STG}	Storage Temperature	-55 to +100	°C		
T _{SOL-I}	Soldering Temperature (Iron) ⁽²⁾⁽³⁾	240 for 5 sec	240 for 5 sec °C		
T _{SOL-F}	Soldering Temperature (Flow) ⁽²⁾⁽³⁾ 260 for 10 sec				
EMITTER					
I _F	Continuous Forward Current	50	mA		
V _R	Reverse Voltage	5	5 V		
P _D	Power Dissipation ⁽¹⁾ 100 mW				
SENSOR					
V _{CEO}	Collector-Emitter Voltage	30	V		
V _{ECO}	Emitter-Collector Voltage	4.5	V		
I _C	Collector Current	20	mA		
P _D	Power Dissipation ⁽¹⁾	100	mW		

Notes:

- 1. Derate power dissipation linearly, on each component, 1.33mW/°C above 25°C.
- 2. RMA flux is recommended.
- 3. Methanol or isopropyl alcohols are recommended as cleaning agents.
- 4. Soldering iron tip 1/16" (1.6mm) from housing.

Electrical/Optical Characteristics (T_A = 25°C)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
EMITTER						
V _F	Forward Voltage	I _F = 20mA		1.2	1.5	V
I _R	Reverse Current	$V_R = 4V$			10	μA
I _{PE}	Peak Emission Wavelength	I _F = 20mA		940		nm
SENSOR						•
I _D	Dark Current	V _{CE} = 10V, I _F = 0mA			200	nA
COUPLED						D
I _{C(ON)}	Collector Current	I _F = 20mA, V _{CE} = 10V	0.5		14	mA
V _{CE (SAT)}	Collector Emitter Saturation Voltage	$I_F = 20 \text{mA}, I_C = 0.1 \text{mA}$			0.4	V
t _r	Rise Time	$V_{CC} = 5V$, $R_L = 100\Omega$,		4		μs
t _f	Fall Time	$I_C = 5mA$		4		μs

Typical Performance Characteristics

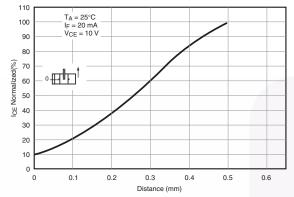


Fig. 1 Collector Current vs. Shield distance

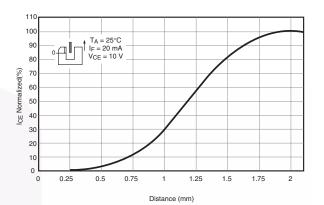


Fig. 2 Collector Current vs. Shield distance

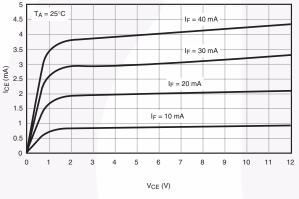


Fig. 3 Collector-Emitter Voltage vs. Collector Current

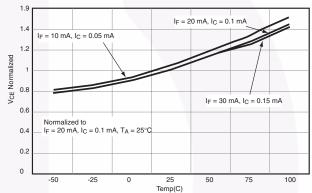


Fig. 4 Collector-Emitter Voltage vs. Temperature

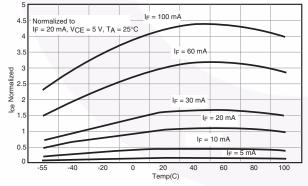


Fig. 5 Collector Current vs. Temperature

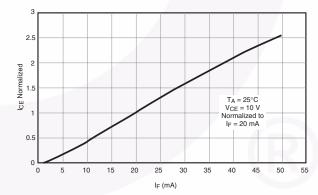


Fig. 6 Collector Current vs. Forward Current

Typical Performance Characteristics (Continued)

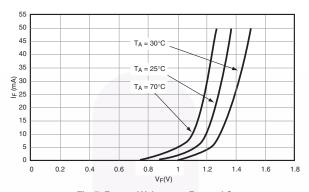


Fig. 7 Forward Voltage vs. Forward Current





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Definition of Terms

Definition of Termo					
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Rev. 140